

74LCX74

Low Voltage Dual D-Type Positive Edge-Triggered Flip-Flop with 5V Tolerant Inputs

General Description

The LCX74 is a dual D-type flip-flop with Asynchronous Clear and Set inputs and complementary (Q, $\bar{Q}$) outputs. Information at the input is transferred to the outputs on the positive edge of the clock pulse. After the Clock Pulse input threshold voltage has been passed, the Data input is locked out and information present will not be transferred to the outputs until the next rising edge of the Clock Pulse input.

Asynchronous Inputs:

- LOW input to $\bar{S}_D$ (Set) sets Q to HIGH level
- LOW input to $\bar{C}_D$ (Clear) sets Q to LOW level
- Clear and Set are independent of clock
- Simultaneous LOW on $\bar{C}_D$ and $\bar{S}_D$ makes both Q and $\bar{Q}$ HIGH

Features

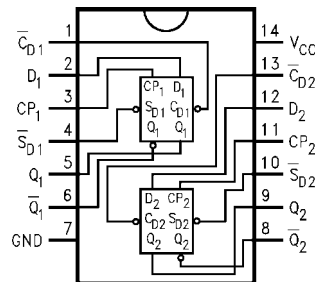
- 5V tolerant inputs
- 2.3V–3.6V V_{CC} specifications provided
- 7.0 ns t_{PD} max ($V_{CC} = 3.3V$), 10 μA I_{CC} max
- Power down high impedance inputs and outputs
- ± 24 mA output drive ($V_{CC} = 3.0V$)
- Implements patented noise/EMI reduction circuitry
- Latch-up performance exceeds 500 mA
- ESD performance:
 - Human body model > 2000V
 - Machine model > 200V

Ordering Code:

Order Number	Package Number	Package Description
74LCX74M	M14A	14-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150 Narrow
74LCX74SJ	M14D	14-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
74LCX74MTC	MTC14	14-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide

Devices also available in Tape and Reel. Specify by appending the suffix letter "X" to the ordering code.

Connection Diagram

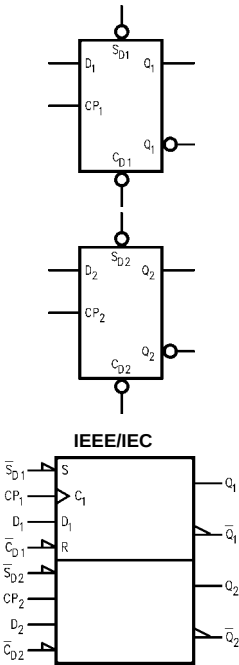


Pin Descriptions

Pin Names	Description
D_1, D_2	Data Inputs
CP_1, CP_2	Clock Pulse Inputs
$\bar{C}_{D1}, \bar{C}_{D2}$	Direct Clear Inputs
$\bar{S}_{D1}, \bar{S}_{D2}$	Direct Set Inputs
$Q_1, \bar{Q}_1, Q_2, \bar{Q}_2$	Outputs

74LCX74 Low Voltage Dual D-Type Positive Edge-Triggered Flip-Flop with 5V Tolerant Inputs

Logic Symbols



Truth Table

(Each Half)

Inputs				Outputs	
$\overline{S}_D$	$\overline{C}_D$	CP	D	Q	$\overline{Q}$
L	H	X	X	H	L
H	L	X	X	L	H
L	L	X	X	H	H
H	H	↗	H	H	L
H	H	↘	L	L	H
H	H	L	X	Q_0	$\overline{Q}_0$

H = HIGH Voltage Level
L = LOW Voltage Level
X = Immaterial
↗ = LOW-to-HIGH Clock Transition
 $Q_0(\overline{Q}_0)$ = Previous $Q(\overline{Q})$ before LOW-to-HIGH Transition of Clock

Absolute Maximum Ratings ^(Note 1)				
Symbol	Parameter	Value	Conditions	Units
V _{CC}	Supply Voltage	−0.5 to +7.0		V
V _I	DC Input Voltage	−0.5 to +7.0		V
V _O	DC Output Voltage	−0.5 to V _{CC} + 0.5	Output in HIGH or LOW State (Note 2)	V
I _{IK}	DC Input Diode Current	−50	V _I < GND	mA
I _{OK}	DC Output Diode Current	−50 +50	V _O < GND V _O > V _{CC}	mA
I _O	DC Output Source/Sink Current	±50		mA
I _{CC}	DC Supply Current per Supply Pin	±100		mA
I _{GND}	DC Ground Current per Ground Pin	±100		mA
T _{STG}	Storage Temperature	−65 to +150		°C

Recommended Operating Conditions ^(Note 4)

Symbol	Parameter	Min	Max	Units	
V _{CC}	Supply Voltage	Operating Data Retention	2.0 1.5	3.6 3.6	V
	V _I	Input Voltage	0	5.5	V
V _O	Output Voltage	HIGH or LOW State	0	V _{CC}	V
I _{OH} /I _{OL}	Output Current	V _{CC} = 3.0V – 3.6V V _{CC} = 2.7V – 3.0V V _{CC} = 2.3V – 2.7V		±24 ±12 ±8	mA
T _A	Free-Air Operating Temperature	−40	85	°C	
Δt/ΔV	Input Edge Rate, V _{IN} = 0.8V–2.0V, V _{CC} = 3.0V	0	10	ns/V	

Note 1: The Absolute Maximum Ratings are those values beyond which the safety of the device cannot be guaranteed. The device should not be operated at these limits. The parametric values defined in the Electrical Characteristics tables are not guaranteed at the Absolute Maximum Ratings. The “Recommended Operating Conditions” table will define the conditions for actual device operation.

Note 2: I_O Absolute Maximum Rating must be observed.

Note 3: Unused inputs must be held HIGH or LOW. They may not float.

DC Electrical Characteristics

Symbol	Parameter	Conditions	V _{CC} (V)	T _A = −40°C to +85°C		Units
				Min	Max	
V _{IH}	HIGH Level Input Voltage		2.3 – 2.7	1.7		V
			2.7 – 3.6	2.0		
V _{IL}	LOW Level Input Voltage		2.3 – 2.7		0.7	V
			2.3 – 3.6		0.8	
V _{OH}	HIGH Level Output Voltage	I _{OH} = −100μA	2.3 – 3.6	V _{CC} - 0.2		V
		I _{OH} = -8 mA	2.3	1.8		
		I _{OH} = −12 mA	2.7	2.2		
		I _{OH} = −18 mA	3.0	2.4		
		I _{OH} = −24 mA	3.0	2.2		
V _{OL}	LOW Level Output Voltage	I _{OL} = 100μA	2.3 – 3.6		0.2	V
		I _{OL} = 8mA	2.3		0.6	
		I _{OL} = 12 mA	2.7		0.4	
		I _{OL} = 16 mA	3.0		0.4	
		I _{OL} = 24 mA	3.0		0.55	
I _I	Input Leakage Current	0 ≤ V _I ≤ 5.5V	2.3 – 3.6		±5.0	μA
I _{OFF}	Power-Off Leakage Current	V _I or V _O = 5.5V	0		10	μA
I _{CC}	Quiescent Supply Current	V _I = V _{CC} or GND	2.3 – 3.6		10	μA
		3.6V ≤ V _I ≤ 5.5V	2.3 – 3.6		±10	
ΔI _{CC}	Increase in I _{CC} per Input	V _{IH} = V _{CC} −0.6V	2.3 – 3.6		500	μA

AC Electrical Characteristics

Symbol	Parameter	T _A = −40°C to +85°C, R _L = 500Ω						Units
		V _{CC} = 3.3V ± 0.3V		V _{CC} = 2.7V		V _{CC} = 2.5V ± 0.2V		
		C _L = 50 pF		C _L = 50 pF		C _L = 30 pF		
		Min	Max	Min	Max	Min	Max	
t _{MAX}	Maximum Clock Frequency	150		150		150		MHz
t _{PHL}	Propagation Delay	1.5	7.0	1.5	8.0	1.5	8.4	ns
t _{PLH}	CP _n to Q _n or Q̄ _n	1.5	7.0	1.5	8.0	1.5	8.4	
t _{PHL}	Propagation Delay	1.5	7.0	1.5	8.0	1.5	8.4	ns
t _{PLH}	C̄ _{Dn} or S̄ _{Dn} to Q _n or Q̄ _n	1.5	7.0	1.5	8.0	1.5	8.4	
t _S	Setup Time	2.5		2.5		4.0		ns
t _H	Hold Time	1.5		1.5		2.0		ns
t _W	Pulse Width CP	3.3		3.3		4.0		ns
t _W	Pulse Width and C̄ _D , S̄ _D	3.3		3.6		4.0		ns
t _{REC}	Recovery Time	2.5		3.0		4.5		ns
t _{OSHL}	Output to Output Skew		1.0					ns
t _{OSLH}	(Note 4)		1.0					

Note 4: Skew is defined as the absolute value of the difference between the actual propagation delay for any two separate outputs of the same device. The specification applies to any outputs switching in the same direction, either HIGH-to-LOW (t_{OSHL}) or LOW-to-HIGH (t_{OSLH}).

Dynamic Switching Characteristics

Symbol	Parameter	Conditions	V_{CC} (V)	$T_A = 25^{\circ}\text{C}$	Unit
				Typical	
V_{OLP}	Quiet Output Dynamic Peak V_{OL}	$C_L = 50\text{ pF}, V_{IH} = 3.3V, V_{IL} = 0V$	3.3	0.8	V
		$C_L = 30\text{ pF}, V_{IH} = 2.5V, V_{IL} = 0V$	2.5	0.6	
V_{OLV}	Quiet Output Dynamic Peak V_{OL}	$C_L = 50\text{ pF}, V_{IH} = 3.3V, V_{IL} = 0V$	3.3	-0.8	V
		$C_L = 30\text{ pF}, V_{IH} = 2.5V, V_{IL} = 0V$	2.5	-0.6	

Capacitance

Symbol	Parameter	Conditions	Typical	Units
C_{IN}	Input Capacitance	$V_{CC} = \text{Open}, V_I = 0V \text{ or } V_{CC}$	7	pF
C_{OUT}	Output Capacitance	$V_{CC} = 3.3V, V_I = 0V \text{ or } V_{CC}$	8	pF
C_{PD}	Power Dissipation Capacitance	$V_{CC} = 3.3V, V_I = 0V \text{ or } V_{CC}, f = 10\text{ MHz}$	25	pF

AC Loading and Waveforms

Generic for LCX Family

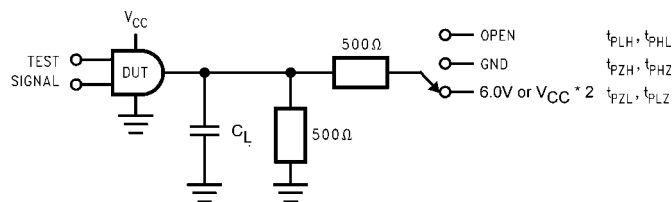
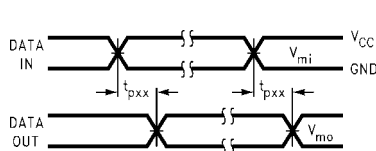
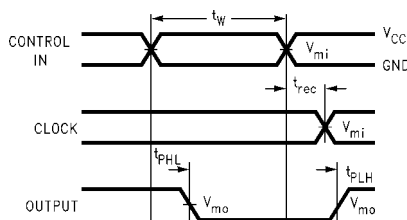


FIGURE 1. AC Test Circuit
(C_L includes probe and jig capacitance)

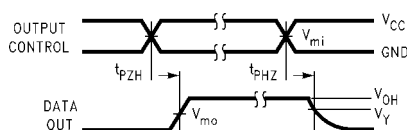
Test	Switch
t_{PLH}, t_{PHL}	Open
t_{PZL}, t_{PLZ}	6V at $V_{CC} = 3.3 \pm 0.3V$ $V_{CC} \times 2$ at $V_{CC} = 2.5 \pm 0.2V$
t_{PZH}, t_{PHZ}	GND



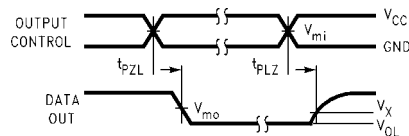
Waveform for Inverting and Non-Inverting Functions



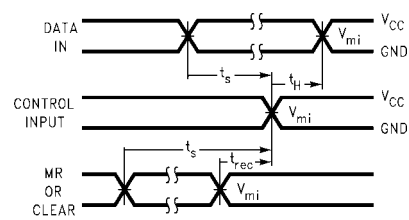
Propagation Delay, Pulse Width and t_{rec} Waveforms



3-STATE Output High Enable and Disable Times for Logic



3-STATE Output Low Enable and Disable Times for Logic



Setup Time, Hold Time and Recovery Time for Logic

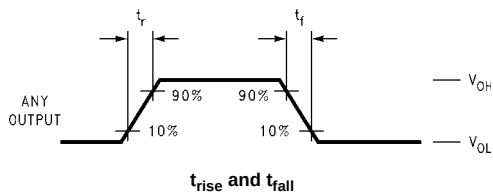
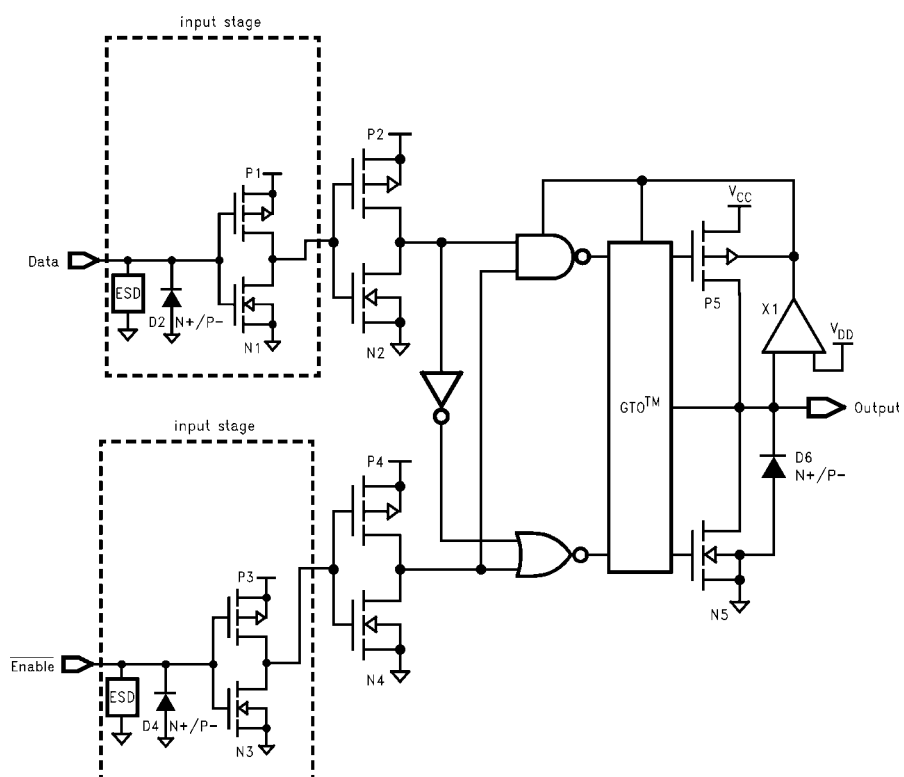
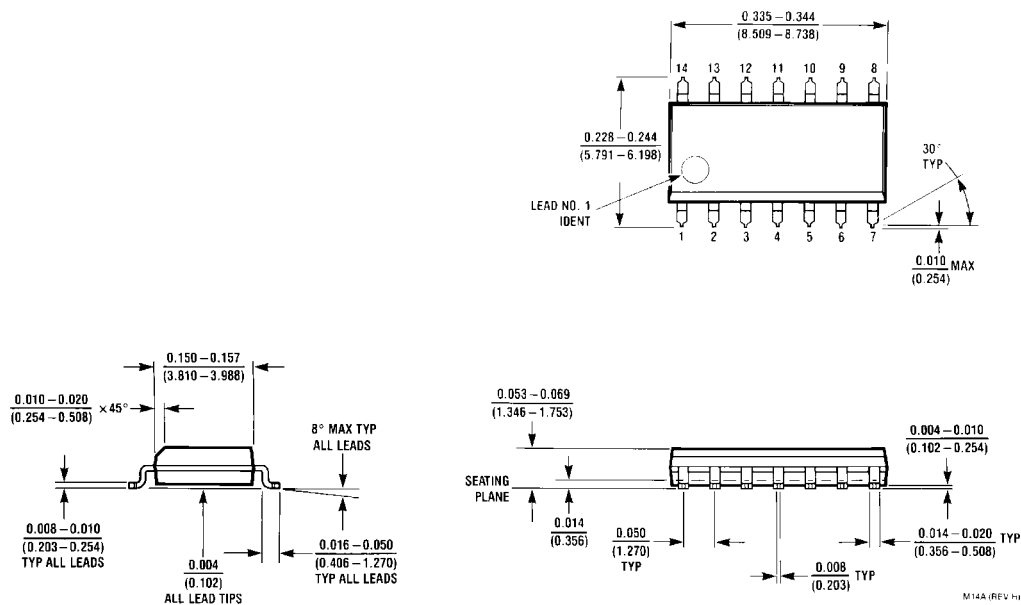


FIGURE 2. Waveforms
(Input Pulse Characteristics; $f = 1\text{MHz}$, $t_r = t_f = 3\text{ns}$)

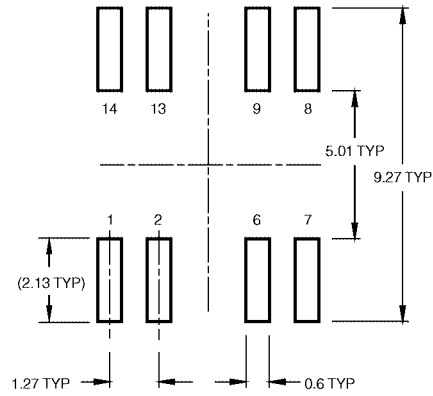
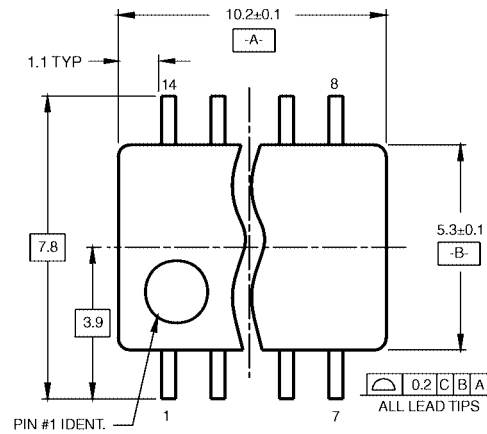
Symbol	V_{CC}		
	$3.3V \pm 0.3V$	$2.7V$	$2.5V \pm 0.2V$
V_{mi}	$1.5V$	$1.5V$	$V_{CC}/2$
V_{mo}	$1.5V$	$1.5V$	$V_{CC}/2$
V_x	$V_{OL} + 0.3V$	$V_{OL} + 0.3V$	$V_{OL} + 0.15V$
V_y	$V_{OH} - 0.3V$	$V_{OH} - 0.3V$	$V_{OH} - 0.15V$



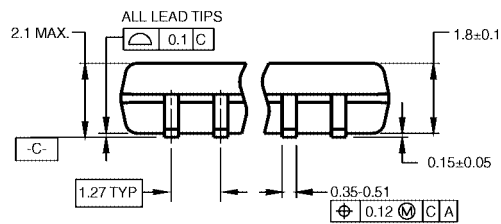
Physical Dimensions inches (millimeters) unless otherwise noted


**14-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150 Narrow
Package Number M14A**

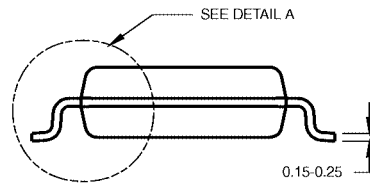
Physical Dimensions inches (millimeters) unless otherwise noted (Continued)



LAND PATTERN RECOMMENDATION



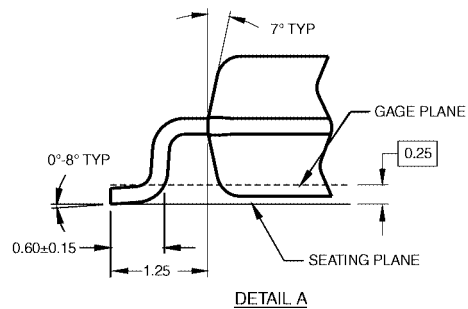
DIMENSIONS ARE IN MILLIMETERS



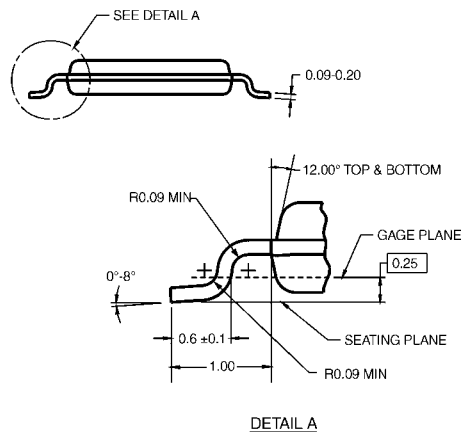
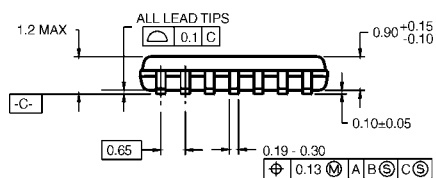
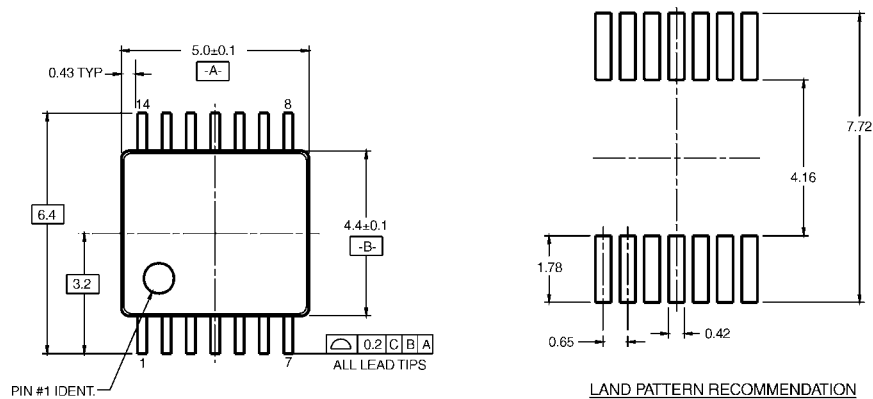
NOTES:

- A. CONFORMS TO EIAJ EDR-7320 REGISTRATION, ESTABLISHED IN DECEMBER, 1998.
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.

M14DRevB1



14-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
Package Number M14D

Physical Dimensions inches (millimeters) unless otherwise noted (Continued)

NOTES:

- A. CONFORMS TO JEDEC REGISTRATION MO-153, VARIATION AB, REF NOTE 6, DATE 7/93.
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.
- D. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M, 1982.

MTC14RevC3

**14-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide
Package Number MTC14**

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